

## *Technical Data Sheet*

### **FeedBond<sup>®</sup> EP-3600-H2**

### ***Non-conductive Die Attach Adhesive***

#### **Description:**

**FeedBond<sup>®</sup>EP-3600-H2** one-component, translucent epoxy adhesive is developed for optoelectronic packaging application. This adhesive can be used for small die sized chip LED and can be applied to automatic die attach equipment.

#### **Application Package:**

LED Chip, GaN Blue and white LED Chip bonding etc.

#### **Characteristics:**

- No yellowing due to heat and light
- Middle viscosity that is adaptable to conventional processing methods such as pin transfer and dispensing.

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Appearance	Translucent		
Viscosity @ 25°C	24000cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25°C	1.5	Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc. @ 5rpm	FT-P008
Grind	< 10μm	Grind meter	FT-P026
Work Life @ 25°C	48hrs	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ -40°C	6months		FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
Standard Cure Condition		60 minutes in oven @160°C	

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

## FeedBond® EP-3600-H2

PHYSIOCHEMICAL PROPERTIES	TEST DESCRIPTION	TEST METHOD
Hardness 85	Shore D	FT-9037
Glass Transition Temperature (Tg) 191°C	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion		
Below Tg( $\alpha_1$ ) 51ppm/°C	TMA Expansion Mode	FT-M016
Above Tg( $\alpha_2$ ) 108ppm/°C		
Dynamic Tensile Modulus		
@25°C 2399MPa	Dynamic Mechanical Thermal Analysis using <1.6 mm thick specimen	FT-M019A
@150°C 1184MPa		
@250°C 305MPa		
MECHANICAL PROPERTIES-POST CURE	TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25°C >50 g/die	3 × 5mil die / PLCC	FT-M012

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### Instruction

**This product is easy to hindered, resulting inhibit the cure.** Avoid the following materials: ①Containing Amin type, Thiol type, acid anhydride. ② Alcohol, Ketone, Polar solvent (DME, NMP). ③The sulfur-containing surface treatment agent.

### Thawing

Place the container to stand vertically for 60mins.**DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

### Storage

Adhesive should be stored @ -40°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Storage Temp.	-42°C ~ -35°C	-22°C ~ -18°C	0°C ~ 5°C	18°C ~ 28°C
Shelf Life	6months	6months	3months	2 days

### Availability

FeedBond® adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.